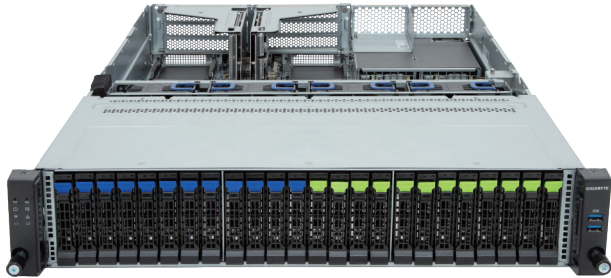


R263-Z32-AAV1

Rack Server - 2U UP 24-Bay NVMe/SATA



Key Features

- Single AMD EPYC™ 9004 Series Processors
- 12-Channel DDR5 RDIMM, 12 x DIMMs
- Dual ROM Architecture
- 1 x 1Gb/s LAN port via Intel® I210-AT
- 12 x 2.5" Gen4 NVMe hot-swap bays
- 12 x 2.5" SATA/SAS hot-swap bays
- 1 x M.2 slot with PCIe Gen3 x4 interface
- 2 x FHHL PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- 1+1 1600W 80 PLUS Titanium redundant power supplies

Application

Networking, Hybrid/Private Cloud Server

Specification

Dimensions	2U (W438 x H87.5 x D710 mm)
Motherboard	MZ33-DC0
CPU	AMD EPYC™ 9005 Series Processors AMD EPYC™ 9004 Series Processors Single processor, cTDP up to 300W - At 30°C ambient, cTDP up to 400W
Socket	1 x LGA 6096 (Socket SP5)
Chipset	System on Chip
Memory	12 x DIMM slots 12-Channel DDR5 RDIMM RDIMM: Up to 4800 MT/s
LAN	1 x 1Gb/s LAN (1 x Intel® I210-AT) - Supports NCSI 1 x 10/100/1000 Mbps Management LAN
Video	Integrated in ASPEED® AST2600 - 1 x VGA port
Storage	Front hot-swap: 12 x 2.5" Gen4 NVMe + 12 x 2.5" SATA/SAS *SAS card is required to support SAS drives. Internal M.2: 1 x M.2 (2280/22110), PCIe Gen3 x4
RAID	Require RAID add-in cards
Expansion Slots	2 x FHHL PCIe Gen5 x16 slots 2 x OCP NIC 3.0 PCIe Gen5 x16 slots - Supports NCSI

I/O Ports	Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 1 x RJ45, 1 x MLAN
Backplane Board	Speed and bandwidth: PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s
Security Modules	1 x TPM header with SPI interface (Optional TPM2.0 kit: CTM010)
Power Supply	1+1 1600W 80 PLUS Titanium redundant power supplies AC Input: 100-240V
System Management	ASPEED® AST2600 Baseboard Management Controller GIGABYTE Management Console web interface
OS Support	Windows Server, Red Hat Enterprise Linux server, Ubuntu, SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor
System Fans	4 x 80x80x38mm (18,300rpm)
Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8%-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Packaging Content	1 x R263-Z32-AAV1, 1 x CPU heatsink, 1 x 2-Section Rail kit 1 x Mini-DP to D-Sub cable Packaging Dimensions: 989 x 594 x 279 mm
Part Numbers	Barebone package (EPYC 9005/9004): 6NR263Z32DR000ABV1* Barebone package (EPYC 9004): 6NR263Z32DR000AAV1* Optional parts: - 3-Section Rail kit (Supports CMA): 25HB2-A56121-K0R - Cable Management Arm: 25HB1-R18300-K0R



Learn more at <https://www.GIGABYTE.com/enterprise>

* All specifications are subject to change without notice. Please visit our website for the latest information.
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